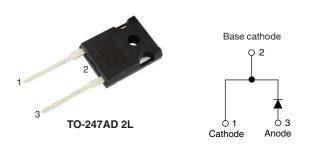


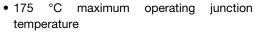
Ultrafast Rectifier, 50 A FRED Pt®

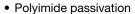


PRIMARY CHARACTERISTICS						
I _{F(AV)}	50 A					
V _R	1200 V					
V _F at I _F at 125 °C	1.95 V					
t _{rr}	57 ns					
T _J max.	175 °C					
Package	TO-247AD 2L					
Circuit configuration	Single					

FEATURES

- Ultrafast and soft recovery
- Optimized forward voltage drop





- · Rugged design
- Good thermal performance
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





RoHS COMPLIANT HALOGEN

FREE

DESCRIPTION / APPLICATIONS

Ultrafast recovery rectifiers designed with optimized performance of forward voltage drop, recovery time, and soft recovery. Polyimide passivated, planar structure, and the platinum doped life time control guarantee, ruggedness, reliability characteristics, and solid value proposition for efficiency and thermal performance.

These devices are intended for use in boost stage in the AC/DC section of SMPS, high frequency output rectification of battery charger, inverters for solar inverters, or as freewheeling diodes in motor drive.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Repetitive peak reverse voltage	V_{RRM}		1200	V			
Average rectified forward current	I _{F(AV)}	T _C = 138 °C, D = 0.50	50				
Non-repetitive peak surge current	I _{FSM}	T_C = 25 °C, t_p = 10 ms, sine wave	400	Α			
Repetitive peak forward current	I _{FRM}		100				
Operating junction and storage temperature	T _J , T _{Stg}		-55 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	MBOL TEST CONDITIONS MIN. TYP. MAX.					
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 500 μA	1200	-	-		
Forward voltage	V _F	I _F = 50 A	ı	2.05	2.55	.37 30 µA	
		I _F = 50 A, T _J = 125 °C	ı	1.95	2.37		
Reverse leakage current	I _R	$V_R = V_R$ rated	-	-	330		
neverse leakage current		$T_J = 125 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	580		
Junction capacitance	C _T	V _R = 200 V	-	55	-	pF	
Series inductance	L _S	Measured to lead 5 mm from package body	-	8	-	nH	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1.0 \text{ A}, dI_F/dt = 10$	00 A/μs, V _R = 30 V	-	57	-		
Reverse recovery time	t _{rr}	T _J = 25 °C	I _F = 50 A dI _F /dt = 100 A/μs V _R = 390 V	-	262	-	ns	
		T _J = 125 °C		-	473	-		
Dook recovery current	I _{RRM}	T _J = 25 °C		-	9.8	-	А	
Peak recovery current		T _J = 125 °C		-	17	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	1280	-	nC	
		T _J = 125 °C		-	4056	-		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Thermal resistance, junction to case	R_{thJC}		-	0.2	0.28			
Thermal resistance, junction to ambient	Thermal resistance, junction to ambient R _{thJA} Typical socket mount		-	31	34	°C/W		
Thermal resistance, case to heat sink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.22	0.32			
Weight			-	0.2	-	g		
vveignit			-	0.07	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C		
Marking device		Case style: TO-247AD 2L	50EPU12L					

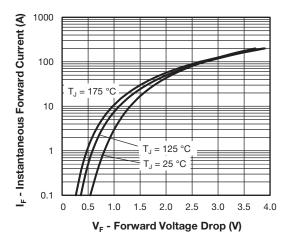


Fig. 1 - Typical Forward Voltage Drop Characteristics

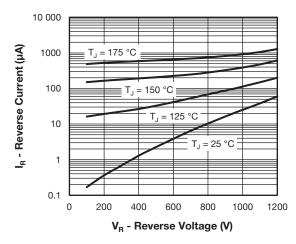


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

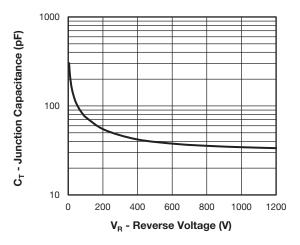


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

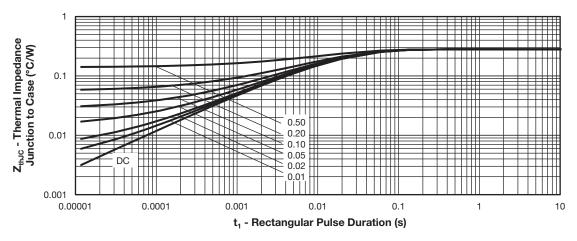


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

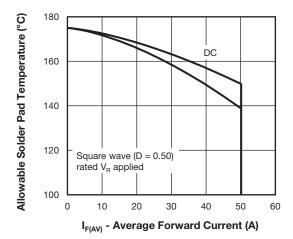
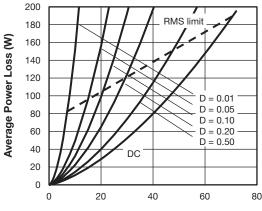


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current



I_{F(AV)} - Average Forward Current (A)

Fig. 6 - Forward Power Loss Characteristics



www.vishay.com

Vishay Semiconductors

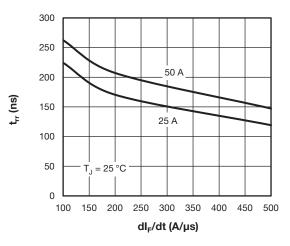


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

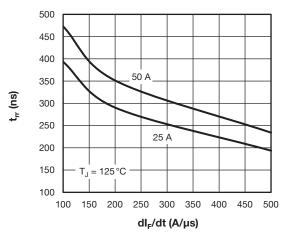


Fig. 8 - Typical Reverse Recovery Time vs. dl_F/dt

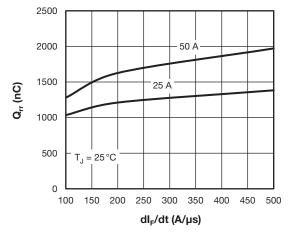


Fig. 9 - Typical Stored Charge vs. dI_F/dt

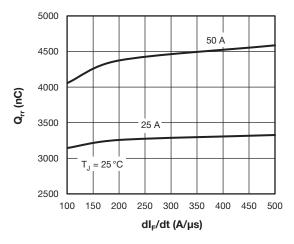


Fig. 10 - Typical Stored Charge vs. dl_F/dt

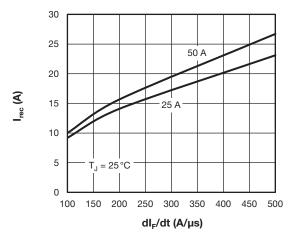


Fig. 11 - Typical Reverse Current vs. dl_F/dt

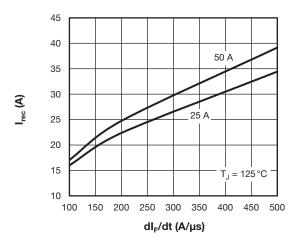
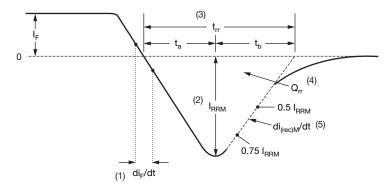


Fig. 12 - Typical Reverse Current vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RBM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RBM}

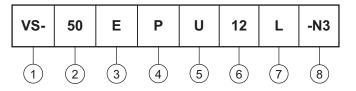
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 13 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- 2 Current rating (50 = 50 A)
- Circuit configuration: E = single diode
- 4 P = TO-247 package
- 5 Process type:

U = ultrafast recovery

- **6** Voltage rating (12 = 1200 V)
- 7 L = long lead
- 8 Environmental digit:

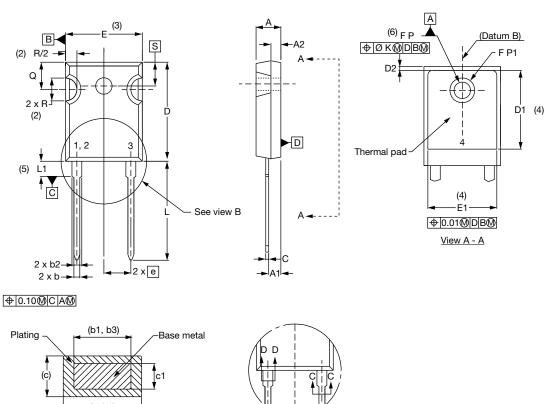
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N QUANTITY PER TUBE MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION							
VS-50EPU12L-N3	25	500	Antistatic plastic tube				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95536				
Part marking information	www.vishay.com/doc?95648				

TO-247AD 2L

DIMENSIONS in millimeters and inches



View B

SYMBOL	MILLIM		MILLIMETERS		INC	HES	NOTES
STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES		
А	4.65	5.31	0.183	0.209			
A1	2.21	2.59	0.087	0.102			
A2	1.50	2.49	0.059	0.098			
b	0.99	1.40	0.039	0.055			
b1	0.99	1.35	0.039	0.053			
b2	1.65	2.39	0.065	0.094			
b3	1.65	2.34	0.065	0.092			
С	0.38	0.89	0.015	0.035			
c1	0.38	0.84	0.015	0.033			
D	19.71	20.70	0.776	0.815	3		
D1	13.08	-	0.515	-	4		
D2	0.51	1.35	0.020	0.053			

Section C - C, D - D

SYMBOL	MILLIN	IETERS	INC	HES	NOTES	
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
E	15.29	15.87	0.602	0.625	3	
E1	13.46	-	0.53	-		
е	5.46	BSC	0.215	BSC		
ØK	0.2	254	0.0	10		
L	19.81	20.32	0.780	0.800		
L1	3.71	4.29	0.146	0.169		
ØΡ	3.56	3.66	0.14	0.144		
Ø P1	-	6.98	-	0.275		
Q	5.31	5.69	0.209	0.224		
R	4.52	5.49	0.178	0.216		
S	5.51 BSC		0.217	BSC		
<u> </u>						

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.